

# 镀金电子封装热沉芯片W90Cu10性能

产品名称	镀金电子封装热沉芯片W90Cu10性能
公司名称	陕西欣龙金属机电有限公司
价格	1.00/件
规格参数	导电率:27 硬度:260 密度:16.75
公司地址	中国 陕西 西安市 西安市经济开发区
联系电话	029-82127495 13991390727

## 产品详情

### 热沉材料 Heat Sink

功率电子器件和电路在运行时会产生大量的热。热沉材料有助于消除芯片热量,将其传输到其他介质,维持芯片稳定工作。 Power electronics and circuits produce a lot of heat when they work. Heat sink materials help to eliminate chip heat, transferring it to other media and keeping the chip stable

钼铜、钨铜、铜-钼-铜(CMC)、铜-钼铜-铜(Cu/MoCu/Cu)和多层式铜-钼-铜(S-CMC)材料结合了钼、钨的低热膨胀率和铜的高热导率,可有效释放电子器件的热量,有助于冷却IGBT模块、RF功率放大器、LED芯片等各种产品,可用于大规模集成电路和大功率微波器件中作为金属基片、热控板、热沉材料和引线框架。 Molybdenum copper, tungsten copper, and some sandwich materials such as CMC, Cu/Mocu/Cu,S-CMCcombined with low thermal expansion rate of molybdenum, tungsten and high thermal conductivity of can effectively release electronics heat and contribute cooling IGBT module, RF power amplifier, LED and other products. They are thus applied as metal substrate, thermal control, heat sink and the lead in large-scale integrated circuit and high power microwave devices .

我们可以按照客户要求提供以上各种材料的板材和成品。如果需要,也可以提供镀镍、金产品。 We can offer Wcu, Mocu, CMC, Cu/Mocu/Cu and s-cmc finished and semi-finished products. And we can also provide these products coated with Ni or Niau as customers need

专业的电子封装产品镀金应该怎么样选择一个合适的厂家,专业厂家提供优质镀金服务。

牌号Material	钨含量Tungsten Content	铜含量Copper Content	密度Density	热导率Thermal Conductivity at2	热膨胀系数CTE at25
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	Wt%	Wt%	g/cm <sup>3</sup>	W/M - K	( 10-6/K )
W90Cu10	90 ± 1	Balance	17.0	180-190	6.5
W85Cu15	85 ± 1	Balance	16.4	190-200	7.0
W80Cu20	80 ± 1	Balance	15.6	200-210	8.3
W70Cu30	70 ± 1	Balance	14.9	220-230	9.0
W50Cu50	50 ± 1	Balance	12.2	310-340	12.5

公司网站: <http://www.sxxljs.com>

手机 : (86)13991390727 赵女士

微信 : sxxljs

Q Q : 1450014646